



Handwritten initials and a dollar sign.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Min-Lung HUANG et al. Confirmation No: 8687
Appl. No. : 10/820,855
Filed : April 9, 2004
Title : Under Bump Metallization Structure Of A Semiconductor Wafer

TC/A.U. : 2813
Examiner : D. S. Blum

Docket No.: : HUAN3262/REF
Customer No: : 23364

PETITION FOR EXTENSION OF TIME

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicants request that the period for response to the outstanding official action in this case be extended pursuant to 37 CFR 1.136 (a) for ONE (1) month to August 11, 2006.

The fee set in 37 CFR 1.17(a)(1) for a one month extension of time is \$120.00 and a check in this amount is submitted herewith. Please charge any additional fee required for this extension to Deposit Account No. 02-0200.

Respectfully submitted,
BACON & THOMAS, PLLC

By: Scott A. Brairton
Scott A. Brairton
Registration No. 55,020

625 Slaters Lane, 4th Fl.
Alexandria, Virginia 22314
Phone: (703) 683-0500
Facsimile: (703) 683-1080

08/09/2006 SDENB081 00000075 10820855

01 FC:1251

120.00 0p

SAB/cmd
1.MO.EXT.wpd

August 8, 2006